

FEE TRANSMITTAL

Electronic Version v08

Stylesheet Version v08.0

Title of Invention	METHOD FOR FORMING ROBUST SOLDER INTERCONNECT STRUCTURES BY REDUCING EFFECTS OF SEED LAYER UNDERETCHING
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Application Number :

Date :

First Named Applicant: Kamalesh K. Srivastava

Attorney Docket Number: FIS920030359US1

TOTAL FEE AUTHORIZED \$ 810

Patent fees are subject to annual revisions on or about October 1st of each year.

Filing as large entity

BASIC FILING FEE

Fee Description	Fee Code	Amount \$	Fee Paid \$
Utility Filing Fee	1001	770	770
Subtotal For Basic Filing Fees: \$ 770			

EXTRA CLAIM FEES

Fee Description	Extra Claim	Fee Code	Amount \$	Fee Paid \$
Total Claims : 20	0	1202	18	0
Independent Claims : 3	0	1201	86	0
Subtotal For Extra Claims Fees: \$ 0				

ASSIGNMENT FEES

Fee Description	Property Number	Quantity	Fee Code	Amount \$	Fee Paid \$
Recording Each Patent Assignment Per Property Fee	00000000	1	8021	40	40
Subtotal For Additional Fees: \$40					

AUTHORIZED BILLING INFORMATION

The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:

Deposit account number: 090458

Deposit name: INTERNATIONAL BUSINESS MACHINES CORPORATION

Deposit authorized name: JAMES J. CIOFFI

Signature: JAMES J. CIOFFI/ S /

Date (YYYYMMDD):

2004-03-16

Charge Assignment Fees Required Under 37 C.F.R. Section 1.21 (h).

Charge Any Additional Fee Required Under 37 C.F.R. Sections 1.16 and 1.17.